502494867 09/13/2013

PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	SECURITY AGREEMENT

CONVEYING PARTY DATA

Name	Execution Date
MSI Acquisition Corp.	08/30/2013

RECEIVING PARTY DATA

Name:	The PrivateBank and Trust Company
Street Address:	1401 S. Brentwood Blvd.
City:	St. Louis
State/Country:	MISSOURI
Postal Code:	63144

PROPERTY NUMBERS Total: 16

Property Type	Number
Patent Number:	8469690
Patent Number:	8469688
Patent Number:	8029712
Patent Number:	7744805
Patent Number:	7438548
Patent Number:	7326897
Patent Number:	7211776
Patent Number:	7151243
Patent Number:	7084382
Patent Number:	7026592
Patent Number:	6696844
Patent Number:	6013074
Patent Number:	5697925
Patent Number:	4753739
Application Number:	61728490

CH $640.00 8469690

Application Number:	61728571

CORRESPONDENCE DATA

Fax Number: 3146673633

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

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ATTORNEY DOCKET NUMBER:	53275-101163
NAME OF SUBMITTER:	Steven M. Ritchey
Signature:	/Steven M. Ritchey/
Date:	09/13/2013

Total Attachments: 6
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PATENT SECURITY AGREEMENT

THIS PATENT SECURITY AGREEMENT (this "Agreement"), is dated as of August 30, 2013, and is by MSI Acquisition Corp., a Missouri corporation ("Grantor"), in favor of The PrivateBank and Trust Company ("Lender").

Recitals

A. Machine Solutions, Inc., an Arizona corporation, Grantor and Lender have entered into a Loan and Security Agreement dated as of November 21, 2011 (as amended, restated, supplemented or otherwise modified from time to time, the "Loan Agreement"), pursuant to which Lender has agreed to make loans to Grantor and issue letters of credit on behalf of Grantor.

B. Pursuant to the Loan Agreement, Grantor is required to execute and deliver to Lender this Agreement.

C. Pursuant to the terms of the Loan Agreement, Grantor has granted to Lender a security interest in substantially all the assets of Grantor, including all right, title and interest of Grantor in, to, and under all now owned and hereafter acquired patents, patent applications and patent licenses, and all products and proceeds thereof (other than any of the foregoing constituting Excluded Property), to secure the payment and performance of the Obligations.

Agreement

In consideration of the mutual agreements set forth herein and in the Loan Agreement, Grantor does hereby grant to Lender, a continuing security interest and lien in all of Grantor's right, title and interest in, to and under the following, whether presently existing or hereafter created or acquired (other than any of the following constituting Excluded Property) to secure the payment and performance of the Obligations:

(1) each patent and patent application, including, without limitation, each patent and patent application referred to in Schedule 1, together with any reissues, continuations or extensions thereof and all goodwill associated therewith;

(2) each patent license, including, without limitation, each patent license listed on Schedule 1, together with all goodwill associated therewith; and

(3) all products and proceeds of the foregoing, including, without limitation, any claim by Grantor against third parties for past, present or future infringement of any patent, including, without limitation, any patent referred to in Schedule 1, any patent issued pursuant to a patent application referred to in Schedule 1 and any patent licensed under any patent license listed on Schedule 1 (items 1 through 3 being herein collectively referred to as the "Patent Collateral").

This security interest and lien is granted in conjunction with the security interests and liens granted to Lender pursuant to the Loan Agreement and subject to limitations set forth therein.

Grantor hereby acknowledges and affirms that the rights and remedies of Lender with respect to the security interests and liens in the Patent Collateral made and granted hereby are more fully set forth in the Loan Agreement, the terms and provisions of which are incorporated by reference herein as if fully set forth herein. Capitalized terms used but not defined herein have the respective meanings ascribed thereto in the Loan Agreement. This Agreement is made under and shall be governed by the internal laws of the State of Illinois applicable to contracts made and to be performed entirely within such state, without regarding to conflict of laws principles thereunder.

[signature page follows]

Grantor has caused this Patent Security Agreement to be duly executed by its duly authorized officer thereunto as of the date first set forth above.

MSI Acquisition Corp., a Missouri corporation

By: ________________________
Print Name: Ryan Gable
Title: Chairman

Acknowledged:

The PrivateBank and Trust Company

By: ________________________
Print Name: Tom Shaner
Title: Managing Director

Grantor has caused this Patent Security Agreement to be duly executed by its duly authorized officer thereunto as of the date first set forth above.

MSI Acquisition Corp., a Missouri corporation

By: ______________________________
Print Name: ______________________________
Title: ______________________________

Acknowledged:

The PrivateBank and Trust Company

By: ______________________________
Print Name: Tom Shaner
Title: Managing Director

SIGNATURE PAGE TO PATENT SECURITY AGREEMENT OF MSI ACQUISITION CORP.

SCHEDULE 1
to
PATENT SECURITY AGREEMENT

Patents, Patent Applications and Patent Licenses

Issued Patents

Patent No.	Issue Date	Country	Title
8469690	6/25/2013	USA	Apparatus for severing and collecting iv tubing tips
8469688	6/25/2013	USA	Rf generator with multiplexed programmed molds
8029712	10/04/2011	USA	Method for collecting iv tubing tips
7744805	6/29/2010	USA	Method for rapidly heating and cooling a mold
7438548	10/21/2008	USA	Apparatus for rapidly heating and cooling a mold
7326897	02/05/2008	USA	Clip on tubing welder
7211776	5/01/2007	USA	Method for unattended sealing of tubing
7151243	12/19/2006	USA	Method for welding material with a clip on welder
7084382	8/01/2006	USA	Clip on welder for plastic material
7026592	4/11/2006	USA	Clip on thermal welder

Patent No.	Issue Date	Country	Title
6696844	2/24/2004	USA	Apparatus and method for real time determination of materials' electrical properties
6013074	1/11/2000	USA	Apparatus and method for thermal ablation
5697925	12/16/1997	USA	Apparatus and method for thermal ablation
4753739	6/28/1998	USA	Blood bag support system

Pending Patent Applications

Abbreviated Title	Serial No.	Filing Date	Country
600 Watt Amplifier for RF Heating	61/728,490	11/20/2012	USA
ISM Frequency Generator	61/728,571	11/20/2012	USA